

## Freescale Semiconductor

MP3V5050  
Rev 1, 11/2009**Integrated Silicon Pressure Sensor  
On-Chip Signal Conditioned,  
Temperature Compensated and  
Calibrated**

The MP3V5050 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This patented, single element transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

**Features**

- 2.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated Over -40° to +125°C
- Patented Silicon Shear Stress Strain Gauge
- Thermoplastic (PPS) Surface Mount Package
- Multiple Porting Options for Design Flexibility
- Barbed Side Ports for Robust Tube Connection

**MP3V5050  
Series**

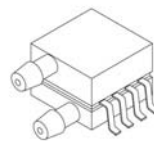
0 to 50 kPa (0 to 7.25 psi)  
0.06 to 2.82 V Output

**ORDERING INFORMATION**

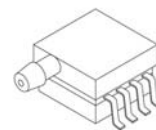
Device Name	Case No.	# of Ports			Pressure Type			Device Marking
		None	Single	Dual	Gauge	Differential	Absolute	
<b>Small Outline Package (MP3V5050 Series)</b>								
MP3V5050DP	1351			•		•		MP3V5050G
MP3V5050GP	1369		•		•			MP3V5050G
MP3V5050GC6U	482A		•		•			MP3V5050G
MP3V5050GC6T1	482A		•		•			MP3V5050G

**SMALL OUTLINE PACKAGES**

MP3V5050GC6U/6T1  
CASE 482A-01



MP3V5050DP  
CASE 1351-01



MP3V5050GP  
CASE 1369-01

## Operating Characteristics

**Table 1. Operating Characteristics** ( $V_S = 3.0$  Vdc,  $T_A = 25^\circ\text{C}$  unless otherwise noted,  $P_1 > P_2$ . Decoupling circuit shown in Figure 4 required to meet electrical specifications.)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range <sup>(1)</sup>	$P_{OP}$	0	—	50	kPa
Supply Voltage <sup>(2)</sup>	$V_S$	2.7	3.0	3.3	Vdc
Supply Current	$I_o$	—	7.0	10	mAdc
Minimum Pressure Offset <sup>(3)</sup> @ $V_S = 3.0$ Volts	$V_{off}$	0.053	0.12	0.188	Vdc
Full Scale Output <sup>(4)</sup> @ $V_S = 3.0$ Volts	$V_{FSO}$	2.752	2.8	2.888	Vdc
Full Scale Span <sup>(5)</sup> @ $V_S = 3.0$ Volts	$V_{FSS}$	—	2.7	—	Vdc
Accuracy <sup>(6)</sup>	—	—	—	±2.5	% $V_{FSS}$
Sensitivity	V/P	—	54	—	mV/kPa
Response Time <sup>(7)</sup>	$t_R$	—	1.0	—	ms
Output Source Current at Full Scale Output	$I_{o+}$	—	0.1	—	mAdc
Warm-Up Time <sup>(8)</sup>	—	—	20	—	ms
Offset Stability <sup>(9)</sup>	—	—	±0.5	—	% $V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range.

3. Offset ( $V_{off}$ ) is defined as the output voltage at the minimum rated pressure.

4. Full Scale Output ( $V_{FSO}$ ) is defined as the output voltage at the maximum or full rated pressure.

5. Full Scale Span ( $V_{FSS}$ ) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

6. Accuracy (error budget) consists of the following:

Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure at  $25^\circ\text{C}$ .

TcSpan: Output deviation over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .

TcOffset: Output deviation with minimum pressure applied, over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .

Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of  $V_{FSS}$  at  $25^\circ\text{C}$ .

7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

8. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.

9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

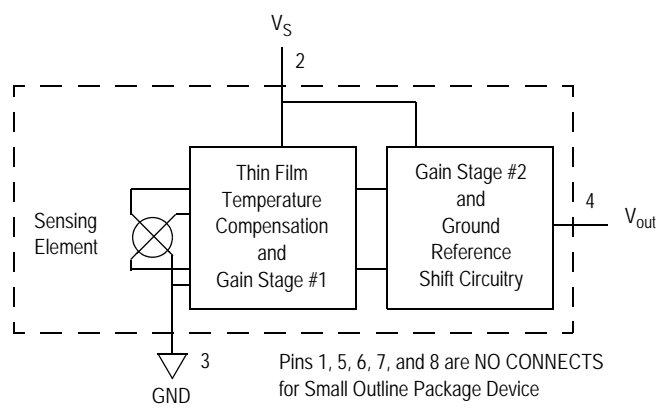
## Maximum Ratings

**Table 2. Maximum Ratings<sup>(1)</sup>**

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	$P_{max}$	200	kPa
Storage Temperature	$T_{stg}$	-40° to +125°	°C
Operating Temperature	$T_A$	-40° to +125°	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.



**Figure 1. Fully Integrated Pressure Sensor Schematic**

## On-chip Temperature Compensation and Calibration

Figure 3 illustrates the Differential/Gauge Sensing Chip in the basic chip carrier (Case 482A). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MP3V5050 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 2 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

Figure 4 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

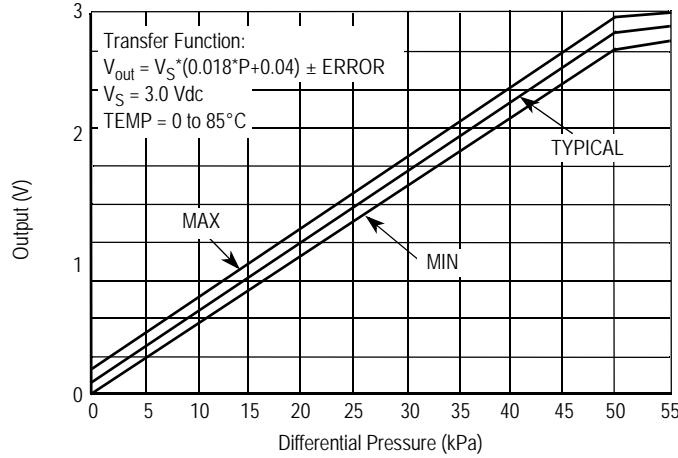


Figure 2. Output vs. Pressure Differential

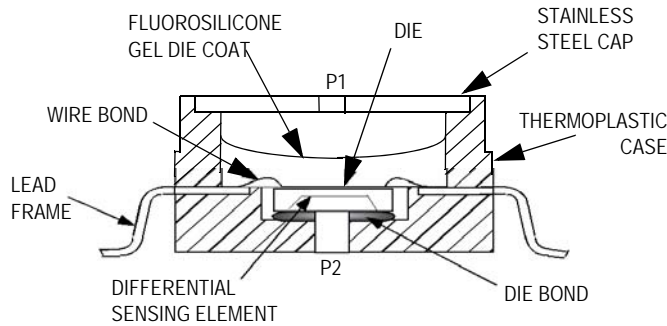


Figure 3. Cross-Sectional Diagram SOP (not to scale)

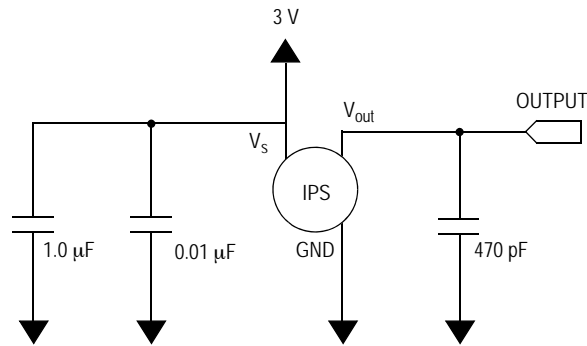


Figure 4. Recommended Power Supply Decoupling and Output Filtering  
 (For additional output filtering, please refer to Application Note AN1646)

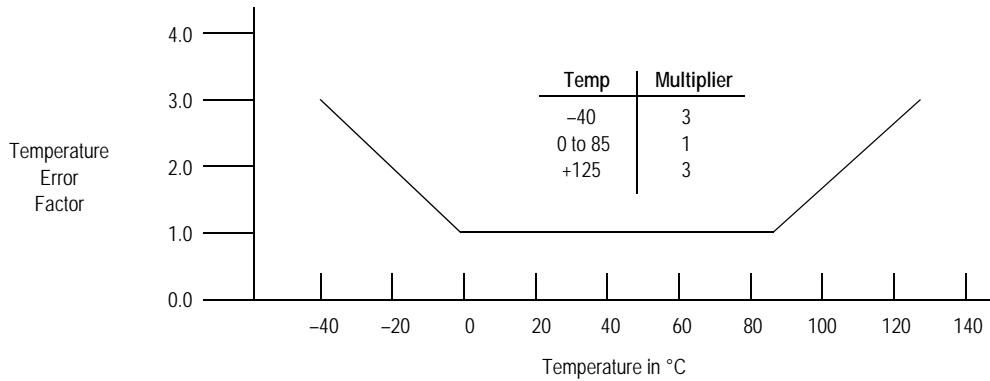
**PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE**

**Transfer Function**

**Nominal Transfer Value:**  $V_{out} = V_S (P \times 0.018 + 0.04)$   
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.018 \times V_S)$   
 $V_S = 3.0 \text{ V} \pm 0.30 \text{ Vdc}$

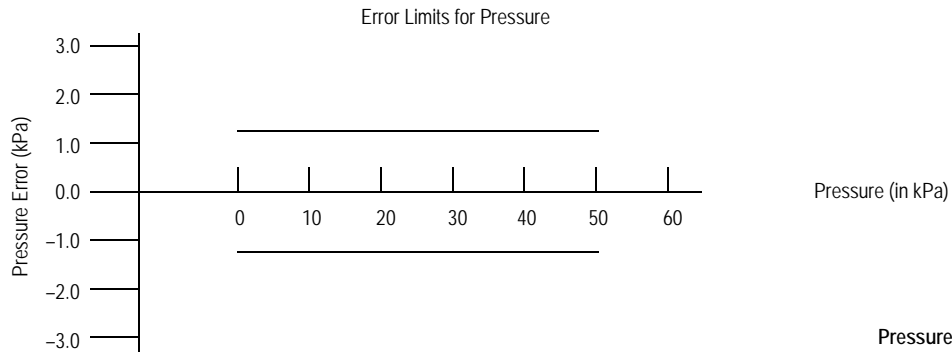
**Temperature Error Band**

**MP3V5050 SERIES**



NOTE: The Temperature Multiplier is a linear response from 0° to -40°C and from 85° to 125°C.

**Pressure Error Band**



**PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE**

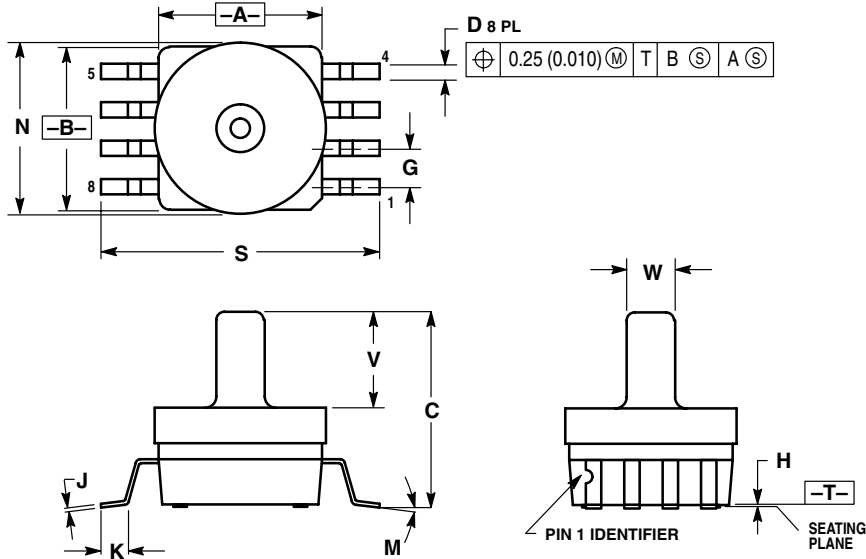
The two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from

harsh media. The MP3V pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

The Pressure (P1) side may be identified by using the table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MP3V5050GP	1369	Side with Port Attached
MP3V5050DP	1351	Side with Part Marking
MP3V5050GC6U/T1	482A	Vertical Port Attached

### PACKAGE DIMENSIONS

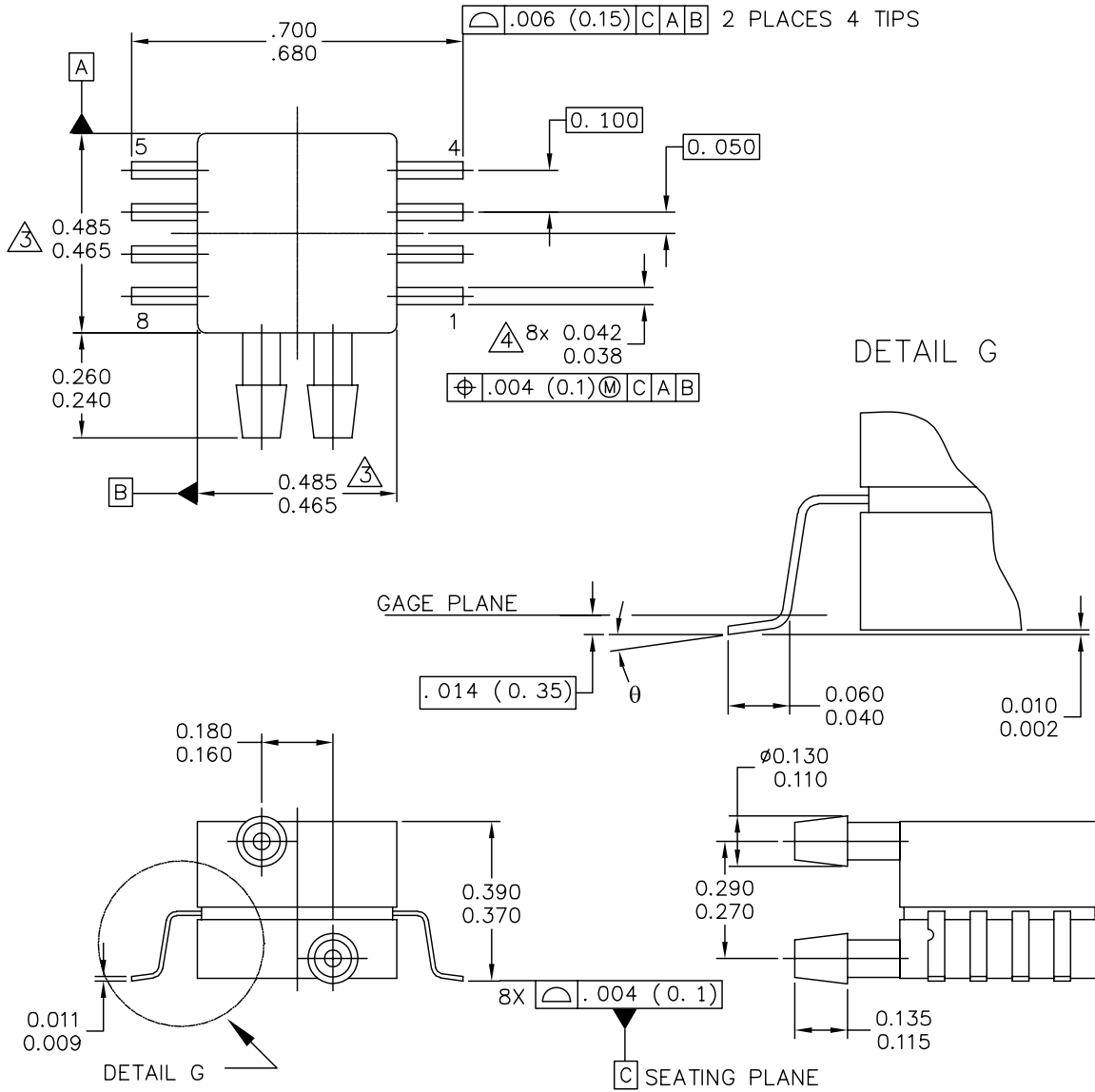


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
  5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0°	7°	0°	7°
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

**CASE 482A-01  
ISSUE A  
UNIBODY PACKAGE**

### PACKAGE DIMENSIONS



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TITLE:  8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A	
	CASE NUMBER: 1351-01	27 JUL 2005	
	STANDARD: NON-JEDEC		

**CASE 1351-01  
ISSUE A  
SMALL OUTLINE PACKAGE**

**PACKAGE DIMENSIONS**

## NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR  
PROTRUSION SHALL BE .008 MAXIMUM.

## STYLE 1:

PIN 1: GND  
PIN 2: +Vout  
PIN 3: Vs  
PIN 4: -Vout  
PIN 5: N/C  
PIN 6: N/C  
PIN 7: N/C  
PIN 8: N/C

## STYLE 2:

PIN 1: N/C  
PIN 2: Vs  
PIN 3: GND  
PIN 4: Vout  
PIN 5: N/C  
PIN 6: N/C  
PIN 7: N/C  
PIN 8: N/C

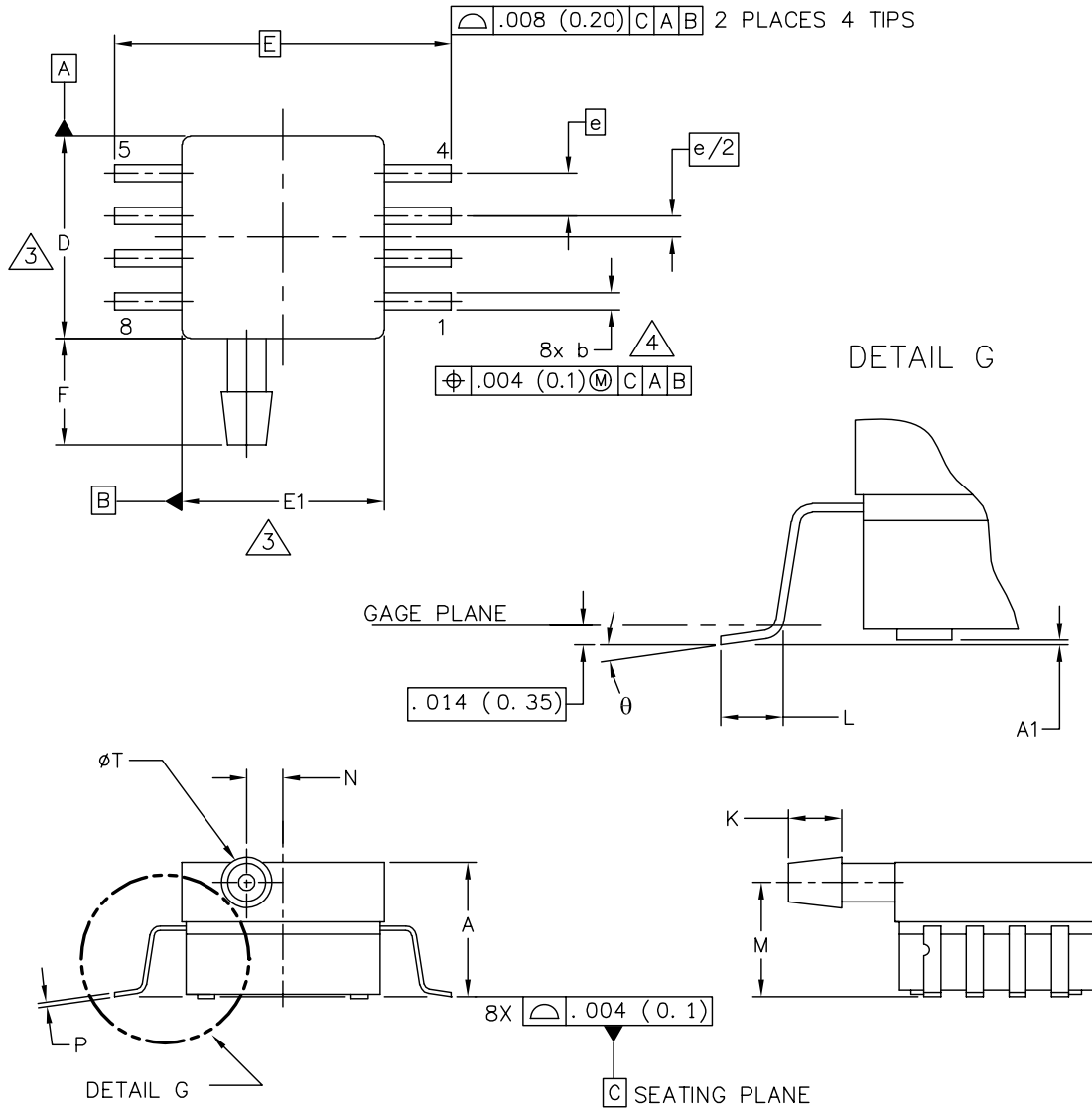
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	STANDARD: NON-JEDEC		

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**CASE 1351-01  
ISSUE A  
SMALL OUTLINE PACKAGE**



### PACKAGE DIMENSIONS



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TITLE:  8 LD SOP, SIDE PORT	DOCUMENT NO: 98ASA99303D	REV: B
	CASE NUMBER: 1369-01	24 MAY 2005
	STANDARD: NON-JEDEC	

**CASE 1369-01  
ISSUE B  
SMALL OUTLINE PACKAGE**

**PACKAGE DIMENSIONS**

## NOTES:

1. CONTROLLING DIMENSION: INCH
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- ③ DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.
- ④ DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.11	7.62	θ	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	-	---	---	---	---
b	.038	.042	0.96	1.07	-	---	---	---	---
D	.465	.485	11.81	12.32	-	---	---	---	---
E	.717 BSC		18.21 BSC		-	---	---	---	---
E1	.465	.485	11.81	12.32	-	---	---	---	---
e	.100 BSC		2.54 BSC		-	---	---	---	---
F	.245	.255	6.22	6.47	-	---	---	---	---
K	.120	.130	3.05	3.30	-	---	---	---	---
L	.061	.071	1.55	1.80	-	---	---	---	---
M	.270	.290	6.86	7.36	-	---	---	---	---
N	.080	.090	2.03	2.28	-	---	---	---	---
P	.009	.011	0.23	0.28	-	---	---	---	---
T	.115	.125	2.92	3.17	-	---	---	---	---
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TITLE:  8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D			REV: B	
					CASE NUMBER: 1369-01			24 MAY 2005	
					STANDARD: NON-JEDEC				

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**CASE 1369-01  
ISSUE B  
SMALL OUTLINE PACKAGE**

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